

ABSTRACT

Provided are an adhesive composition capable of joining with sufficient adhesive strength and capable of achieving high package reliability in a semiconductor device in particular, an adhesive sheet having an adhesive layer composed of the adhesive composition, and a method for manufacturing a semiconductor device that uses the adhesive sheet. The adhesive composition according to the present invention is characterized in comprising an acrylic polymer (A) having a weight-average molecular weight (Mw) of 350,000 or higher obtained by polymerizing an acrylic monomer by living radical polymerization using an organotellurium-containing compound as the polymerization initiator, an epoxy thermosetting resin (B), and a thermosetting agent (C).